



#### 60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

#### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
60V	$9.5 \text{m}\Omega @ V_{GS} = 10V$	45.4A
	$13.3 \text{m}\Omega @ V_{GS} = 4.5 \text{V}$	38.4A

# Features

- Rated to +175°C—Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching (UIS) Test in Production— Ensures More Reliable and Robust End Application
- Low On-Resistance
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Wettable Flank for Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

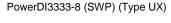
### **Description and Applications**

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

- Backlighting
- Power Management Functions
- DC-DC Converters

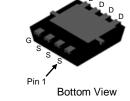
#### **Mechanical Data**

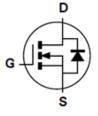
- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072 grams (Approximate)





Top View





**Equivalent Circuit** 

#### **Ordering Information** (Note 5)

Part Number	Case	Packaging
DMTH69M8LFVWQ-7	PowerDI3333-8 (SWP) (Type UX)	2000/Tape & Reel
DMTH69M8LFVWQ-13	PowerDI3333-8 (SWP) (Type UX)	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

#### **Marking Information**



H69 = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 19 = 2019)
WW = Week Code (01 to 53)



# **Maximum Ratings** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	$V_{DSS}$	60	V	
Gate-Source Voltage		$V_{GSS}$	±16	V
Continuous Dunin Comment (Note C) // 40)/	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	Ι <sub>D</sub>	45.4 32.1	А
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	$T_A = +25$ °C $T_A = +100$ °C	Ι <sub>D</sub>	15.9 11.2	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	180	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	I <sub>S</sub>	45	Α	
Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1%)	I <sub>SM</sub>	180	Α	
Avalanche Current, L = 0.1mH	I <sub>AS</sub>	30	Α	
Avalanche Energy, L = 0.1mH		E <sub>AS</sub>	45	mJ

#### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	$P_{D}$	3.6	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\Theta JA}$	41.7	°C/W	
Total Power Dissipation (Note 7) $T_C = +25^{\circ}C$		$P_{D}$	29.4	W
Thermal Resistance, Junction to Case (Note 7)		R <sub>eJC</sub>	5.1	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +175	°C

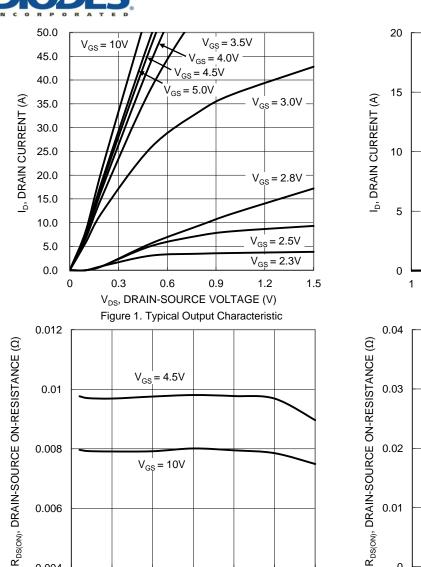
### Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60			٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>		_	1	μΑ	$V_{DS} = 48V, V_{GS} = 0V$	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	3	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D	_	7.7	9.5	mΩ	$V_{GS} = 10V, I_D = 13.5A$	
Static Dialii-Source Off-Resistance	R <sub>DS(ON)</sub>		9.5	13.3	mt2	$V_{GS} = 4.5V, I_D = 11.5A$	
Diode Forward Voltage	$V_{SD}$	_	0.8	1.2	V	$V_{GS} = 0V, I_S = 13.5A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	C <sub>iss</sub>		1925	_	pF	.,	
Output Capacitance	Coss	_	438	_	pF	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	C <sub>rss</sub>		41	_	рF	11 = 11011112	
Gate Resistance	$R_g$		1.7		Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_g$		33.5	_	nC		
Total Gate Charge (V <sub>GS</sub> = 4.5V)	$Q_g$	_	15.6	_	nC	V 20V L 42.5A	
Gate-Source Charge	Qgs	_	4.7	_	nC	$V_{DS} = 30V, I_{D} = 13.5A$	
Gate-Drain Charge	$Q_{gd}$	_	5.3	_	nC	1	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	4.5	_	ns	$V_{DD} = 30V, V_{GS} = 10V,$ $R_G = 6\Omega, I_D = 13.5A$	
Turn-On Rise Time	t <sub>R</sub>	_	8.6	_	ns		
Turn-Off Delay Time	t <sub>D(OFF)</sub>	_	35.9	_	ns		
Turn-Off Fall Time	t <sub>F</sub>		15.7	_	ns		
Body Diode Reverse Recovery Time	t <sub>RR</sub>		18.2	_	ns	I <sub>F</sub> = 13.5A, di/dt = 400A/μs	
Body Diode Reverse Recovery Charge	$Q_{RR}$	_	33.1	_	nC		

- 6. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
  8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.







I<sub>D</sub>, DRAIN-SOURCE CURRENT (A) Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

15

20

30

10

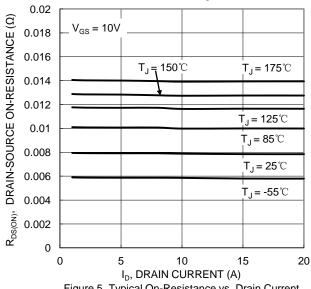


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

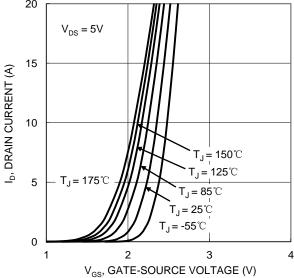
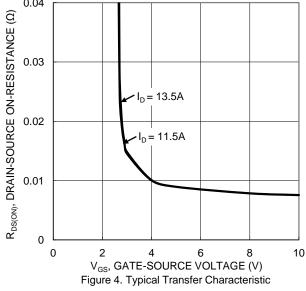


Figure 2. Typical Transfer Characteristic



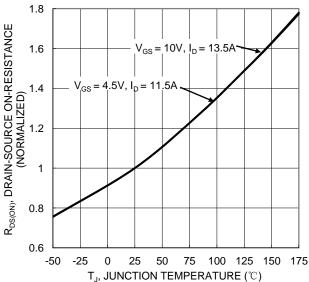
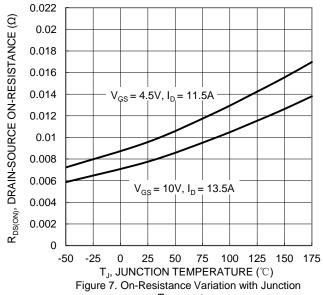


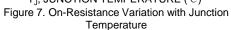
Figure 6. On-Resistance Variation with Junction Temperature

0.004









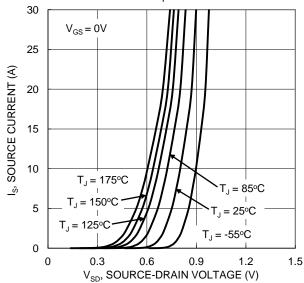
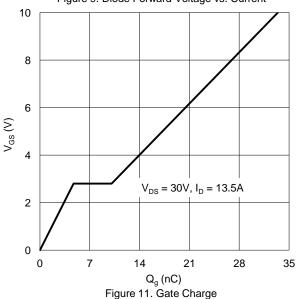


Figure 9. Diode Forward Voltage vs. Current



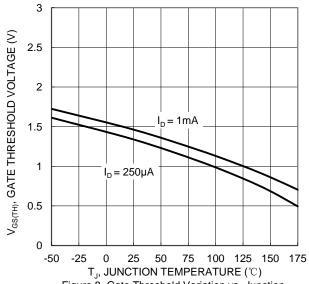
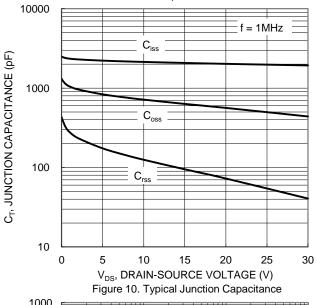
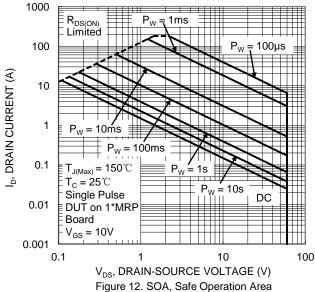


Figure 8. Gate Threshold Variation vs. Junction Temperature







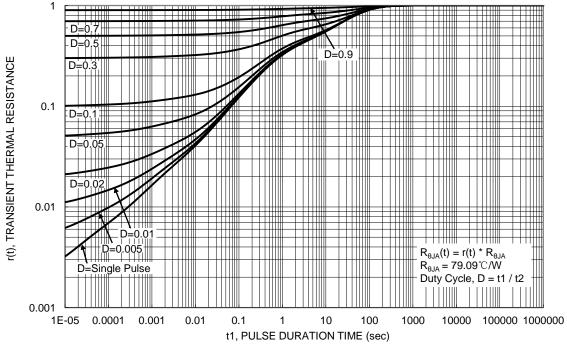


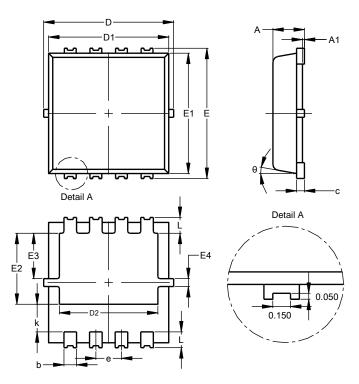
Figure 13. Transient Thermal Resistance



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)

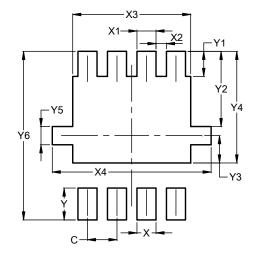


PowerDI3333-8 (SWP)						
(Type UX)						
Dim	Min Max Typ					
Α	0.75	0.85	0.80			
A1	0.00	0.05	_			
b	0.25	0.40	0.32			
С	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Е	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	_	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)



Dimensions	value (in mm)
С	0.650
X	0.420
X1	0.420
X2	0.230
Х3	2.600
X4	3.500
Y	0.700
Y1	0.550
Y2	1.650
Y3	0.600
Y4	2.450
Y5	0.400
Y6	3.700



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